

In Th Claims:

Claims 1-3 (cancelled)

4. (currently amended) The cleaning wipe of Claim 4 23 wherein the ~~surface active agent acetylenic diol~~ is present in the range of 0.01% to 0.3% by weight.

5. (currently amended) The cleaning wipe of Claim 4 4 wherein the ~~ratio of surface active agent acetylenic diol~~ is present in the range of 0.05% to 0.2% by weight.

6. (currently amended) The cleaning wipe of Claim 4 23 wherein the ~~low-volatile organic chemical property of the surface active agent acetylenic diol has~~ is a vapor pressure of at least 1×10^{-4} torr at 25°C.

7. (currently amended) The cleaning wipe of Claim 4 6 wherein the ~~low-nonvolatile residue property of surface active agent is acetylenic diol has~~ a vapor pressure of at least 1×10^{-3} torr at 25°C.

8. (currently amended) The cleaning wipe of Claim 4 23 wherein the ~~surface active agent acetylenic diol~~ is dimethyl octynediol.

9. (currently amended) The cleaning wipe of Claim 4 23 wherein the ~~surface active agent acetylenic diol~~ is tetramethyl decynediol.

10. (currently amended) The cleaning wipe of Claim 4 23 wherein the wipe substrate is selected from the group consisting of: cotton, abaca, polyester, nylon, polyester/cellulose, rayon, polypropylene, rayon/polyester, polypropylene/cellulose, polyurethane, cotton/polyester and mixtures thereof.

11. (currently amended) The cleaning wipe of Claim 4 23 wherein the surface active agent acetylenic diol is selected from the group consisting of: dimethyl octynediol; tetramethyl decynediol; 2,6,9,13-tetramethyl-2,12-tetradecadien-7-yne-6-9-diol; 2,6,9-trimethyl-2-decen-7-yne-6-9-diol; 7,10-dimethyl-8-hexadecyne-7,10-diol; 2,4,7,9-tetramethyl-5-decyne-4,7-diol; 4,7-dimethyl-5-decyne-4,7-diol; 3,6-diethyl-4-octyne-3,6-diol; 2,5-dicycloprpyl-3-hexyne-2,5-diol; 2,5-diphenyl-3-hexyne-2,5-diol; 3,5-dimethyl-1-hexyn-3-ol, 2,5,8,11-tetramethyl-6-dodecyne-5,8-diol; and mixtures thereof.

12. (cancelled)

13. (currently amended) The cleaning wipe of Claim 4 23 wherein the wipe substrate is a fibrous substrate.

14. (currently amended) The cleaning wipe of Claim 4 23 wherein the wipe substrate is a woven fibrous substrate.

15. (currently amended) The cleaning wipe of Claim 4-23 wherein the wipe substrate is a nonwoven fibrous substrate.

16. (currently amended) The cleaning wipe of Claim 4-23 wherein the wipe substrate is a sponge.

17. (currently amended) The cleaning wipe of Claim 4-23 wherein the water is high purity water.

18. (currently amended) The cleaning wipe of Claim 4-23 wherein the water is deionized water.

19. (currently amended) The cleaning wipe of Claim 4-23 wherein the water is distilled water.

20. (currently amended) A prewetted cleaning wipe for cleaning surfaces in an electronic materials fabricating area having a low volatile organic chemical content in the range of 0.001% to 0.5% by weight and low nonvolatile residue property of at least 1×10^{-4} torr at 25°C comprising: a woven fibrous polyester/cellulose wipe substrate wetted with an aqueous solution consisting essentially of high purity water selected from the group consisting of distilled water and deionized water, and an effective amount from 0.001 % to 0.5% by weight of an acetylenic diol surface active agent selected from the group consisting of dimethyl octynediol, tetramethyl decyndiol and mixtures thereof.

21. (cancelled)

22. (currently amended) The cleaning wipe of Claim 20 wherein the acetylenic diol surface active agent is in the range of approximately present in an amount from 0.05% to 0.2% by weight.

23. (new) A cleaning wipe for cleaning surfaces in an electronic materials fabricating area, the wipe comprising:

an aqueous solution consisting essentially of water and from 0.001% to 0.5% by weight of an acetylenic diol; and

a wipe substrate wetted with the aqueous solution

wherein the cleaning wipe has a low volatile organic chemical content in the range of 0.001% to 0.5% by weight and a low nonvolatile residue property of at least 1×10^{-4} torr at 25°C.